HM511665/L Series

65,536-Word x 16-Bit Dynamic RAM

■ DESCRIPTION

The Hitachi HM511665/HM511665L are CMOS dynamic RAM organized as 65,536-word x 16-bit. HM511665/11665L have realized higher density, higher performance and various functions by employing 0.8 μm CMOS process technology and some new CMOS circuit design technologies. The HM511665/HM511665L offer Fast Page Mode as a high speed access mode.

Multiplexed address input permits the HM511665/ HM511665L to be packaged in standard 400 mil 40-pin plastic SOJ, standard 475 mil 40-pin plastic ZIP.

■ FEATURES

Single 5V (±10%)High Speed

.....1.1 mW (max) (L-Version)

- Fast Page Mode Capability
- Write per Bit Capability

 3 Variations of Refresh
 RAS Only Refresh
 CAS Before RAS Refresh
 Hidden Refresh

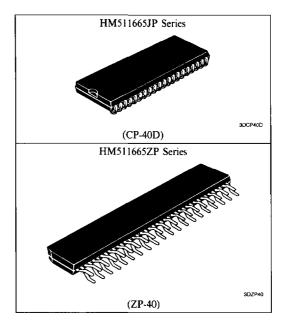
 Battery Back-up Operation HM511665L Series (L-Version)

■ PIN DESCRIPTION

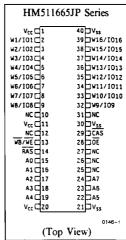
Pin Name	Function
A ₀ -A ₇	Address Input Refresh Address Input
W1/I/O ₁ -W16/I/O ₁₆	Write Select/Data-in/Data-out
RAS	Row Address Strobe
CAS	Column Address Strobe
$\overline{\text{WB}}/\overline{\text{WE}}$	Write per Bit/Read/Write Enable
ŌĒ	Output Enable
v_{CC}^1	Power (+ 5V)
V _{SS} ²	Ground
NC	No Connection

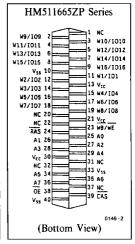
Notes: 1. This device has 3 V_{CC} pins (SOJ: 1, 11, 20 pin/ZIP: 13, 21, 30 pin). All V_{CC} pins must be connected with the same power-supply wiring on the memory board.

 This device has 3 V_{SS} pins (SOJ: 21, 30, 40 pin/ ZIP: 10, 33, 40 pin). All V_{SS} pins must be connected with the same ground wiring on the memory board.



■ PIN OUT





■ ORDERING INFORMATION

Part No.	Access Time	Package
 HM511665JP-8 HM511665JP-10	80 ns 100 ns	400 mil 40-pin Plastic SOJ
 HM511665LJ-8 HM511665LJ-10	80 ns 100 ns	(CP-40D)
 HM511665ZP-8 HM511665ZP-10	80 ns 100 ns	475 mil 40-pin Plastic ZIP
 HM511665LZ-8 HM511665LZ-10	80 ns 100 ns	(ZP-40)



■ BLOCK DIAGRAM WB/WE OE RAS CAS Write Per CAS Control WE Control RAS Control OE Control Bit Control Circuit Circuit Circuit Circuit Circuit W12/1012 W16/1016 W11/1011 W10/1010 W9/109 W15/1015 W14/1014 W13/1Q13 1/OBuster I/OBuffer I/OBuffer I/OBuffer I/OBuffer I/OBuffer I/OBuffer 1/OBuffer W8/IO8 W7/107 W4/104 W3/103 W2/102 W1/101 W6/106 W5/105 I/OBuffer I/OBuffer I/OBuffer I/OBuffer 1/OBuffer I/OBuffer I/OBuffer I/OBuffer Column 128k 128k 128k 128k Column 128k Column 128k 128k Column 128k Memory Decoder Memory Memory Memory Memory Memory Memory Decoder Memory Decoder Decoder Cell Sense Cell Cell Sense Cell Cell Sense Cell Cell Sense Cell Array Amp & Array Array Amp & Array Array Amր & **Array** Array Λmp & Array 1/0 Bus I/O Bus I/O Bus I/O Bus Row Decoder & Driver Column Address Buffer Row Address Buffer Address A0-A7 0146-3

■ TRUTH TABLE

	Ir	iputs	I/O	Operation	
RAS	CAS	WB ∕ WE	ŌĒ	W1/I/O ₁ -W16/I/O ₁₆	peration
Н	H	Н	Н	High-Z	Standby
L	H	Н	H	High-Z	Refresh
L	L	Н	L	D _{out}	Read
L	L	L	H	D_{in}	Write
L	L	H	H	High-Z	

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Voltage on Any Pin Relative to VSS	\mathbf{v}_{T}	-1.0 to +7.0	v
Supply Voltage Relative to VSS	v _{cc}	-1.0 to +7.0	v
Short Circuit Output Current	Lout	50	mA
Power Dissipation	P _T	0.8	w
Operating Temperature	T _{opr}	0 to + 70	°C
Storage Temperature	T _{stg}	- 55 to + 125	°C

■ ELECTRICAL CHARACTERISTICS

• Recommended DC Operating Conditions ($T_A = 0 \text{ to } +70^{\circ}\text{C}$)

Pa	rameter	Symbol	Min	Тур	Max	Unit	Note				
Cl. Water			g l v t		Constant Value		0	0	0	v	
Supply Voltage		v_{cc}	4.5	5.0	5.5	v	1				
Input High Volt	age	V _{IH}	2.4	_	6.5	v	1				
Input Low	(Wi/I/Oi Pin)	V _{IL}	- 0.5	_	0.8	v	1, 2				
Voltage	(Others)	VIL	- 1.0	_	0.8	v	1, 2				

Notes: 1. All voltage referenced to VSS.

2. The device will withstand undershoots to the -2V level with a maximum pulse width of 20 ns at the -1.5V level. (See figure 1.)

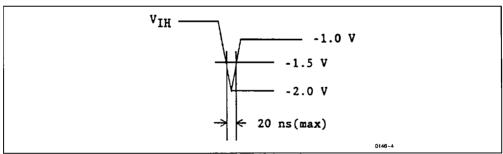


Figure 1. Undershoot of input voltage

• DC Electrical Characteristics ($T_A = 0$ to $+70^{\circ}$ C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$)

Parameter	Symbol		1665-8 1665 L -8		1665-10 665L-10	Unit	Test Conditions	Note
	·	Min	Max	Min	Max			
Operating Current	I _{CC1}	_	115		90	mA	RAS, CAS Cycling t _{RC} = Min	1, 2
Secondless Comment			,	2		mA	$\begin{array}{l} \text{TTL Interface} \\ \overline{\text{RAS}}, \overline{\text{CAS}} = V_{\text{IH}}, \\ D_{\text{out}} = \text{High-Z} \end{array}$	4
Standby Current	I _{CC2}			I		mA	CMOS Interface \overline{RAS} , $\overline{CAS} \ge V_{CC} - 0.2V$ $D_{out} = High-Z$	4
(L-Version) Standby Current	I _{CC2}	ı	200	_	200	μΑ	$\begin{array}{l} \underline{CMOS\ Interface} \\ \underline{RAS}, \underline{CAS} = V_{IH} \\ \underline{WE}, \underline{OE}, \underline{Address\ and} \\ \underline{D_{in}} = V_{IH}\ or\ V_{IL} \\ \underline{D_{out}} = \underline{High-Z} \end{array}$	5
RAS Only Refresh Current	I _{CC3}	_	115	_	90	mA	t _{RC} = Min	2
CAS Before RAS Refresh Current	I _{CC6}	_	115	_	90	mA	$t_{RC} = Min$	
Fast Page Mode Current	I _{CC7}	_	100	_	85	mA	t _{PC} = Min	1, 3
(L-Version) Battery Back-up Operating Current (Standby with CBR Refresh)	I _{CC10}	ı	300	_	300	μА	$\begin{array}{l} t_{RC} = 125~\mu s\\ \frac{t_{RAS} \leq 1~\mu s}{WE = V_{IH}} \frac{c_{AS}}{CAS} \approx V_{IL}\\ \hline OE, ~Address and D_{in} = V_{IH}~or~V_{IL}\\ D_{out} = High-Z \end{array}$	5
Input Leakage Current	I _{LI}	- 10	10	- 10	10	μА	$0V \le V_{in} \le 6.5V$	
Output Leakage Current	I _{LO}	- 10	10	- 10	10	μΑ	$0V \le V_{out} \le 5.5V,$ $D_{out} = Disable$	
Output High Voltage	v _{oh}	2.4	v _{cc}	2.4	v_{cc}	v	High $I_{out} = -2.5 \text{ mA}$	
Output Low Voltage	VOL	0	0.4	0	0.4	v	Low I _{out} = 2.1 mA	

Notes: 1. I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.

- 2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.
- 3. Address can be changed once or less while $\overline{CAS} = V_{IH}$.
- 4. Clock voltages (RAS and CAS) must be applied simultaneously with or prior to applying supply voltage.
- 5. $V_{CC} 0.2V \le V_{IH} \le 6.5V$ and $0V \le V_{IL} \le 0.2V$.

• Capacitance ($T_A \approx 25^{\circ}C$, $V_{CC} = 5V \pm 10\%$)

Parameter	Symbol	Тур	Max	Unit	Note
Input Capacitance (Address)	CII	1	5	pF	1
Input Capacitance (Clocks)	C ₁₂	_	7	pF	1
Output Capacitance (Data-in, Data-out)	C _{I/O}		7	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{CAS} = V_{IH}$ to disable D_{out}

• AC Characteristics ($T_A = 0$ to $+70^{\circ}$ C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$)1, 14, 15

Test Conditions

Input Rise and Fall Times:

5 ns

Input Timing Reference Levels:

0.8V, 2.4V

Output Load:

1 TTL Gate + C_L (50 pF) (Including scope and jig)



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Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

Parameter	Symbol		HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Note
		Min	Max	Min	Max]	
Random Read or Write Cycle Time	t _{RC}	135	_	170	_	ns	
RAS Precharge Time	t _{RP}	45	_	60	_	ns	
RAS Pulse Width	tRAS	80	10000	100	10000	ns	
CAS Pulse Width	tCAS	30	10000	40	10000	ns	
Row Address Setup Time	tASR	0		0		ns	
Row Address Hold Time	tRAH	10	-	10	_	ns	
Column Address Setup Time	tASC	0	_	0	-	ns	
Column Address Hold Time	t _{CAH}	15	_	15	_	ns	
RAS to CAS Delay Time	tRCD	20	50	20	60	ns	8
RAS to Column Address Delay Time	tRAD	15	35	15	45	ns	9
RAS Hold Time	trsh	30	_	40	_	ns	
CAS Hold Time	t _{CSH}	80	_	100	_	ns	
CAS to RAS Precharge Time	tCRP	10	_	10	_	ns	
OE to Din Delay Time	todd	15	_	15	_	ns	
OE Delay Time from Din	t _{DZO}	0	_	0	-	ns	
CAS Setup Time from Din	tDZC	0	_	0	_	ns	
Transition Time (Rise and Fall)	t _T	3	50	3	50	ns	7
Refresh Period	tREF	_	4	_	4	ms	
	·KEF	_	32	_	32	ms	L-Version

Read Cycle

Parameter	Symbol		HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Note
		Min	Max	Min	Max	1	
Access Time from RAS	tRAC	_	80	_	100	пѕ	2, 3
Access Time from CAS	tCAC	_	30	_	40	пs	3, 4, 13
Actess Time from Address	t _{AA}	_	45	_	55	ns	3, 5, 13
Access Time from OE	[‡] OAC	_	30	_	40	ns	
Read Command Setup Time	t _{RCS}	0	_	0		ns	
Read Command Hold Time to CAS	tRCH	0	-	0	_	ns	
Read Command Hold Time to RAS	trrh	0	_	0	_	ns	
Column Address to RAS Lead Time	tRAL	45	_	55	_	ns	
Output Buffer Turn-off Time	toffi	0	20	0	20	ns	6
Output Buffer Turn-off to OE	t _{OFF2}	0	15	0	15	ns	6
CAS to Din Delay Time	tCDD	20	_	20	_	ns	
RAS Hold Time Referenced to OE	troh	10	_	10	_	ns	

Write Cycle

Parameter	Symbol	HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Unit	Note
	•	Min	Max	Min	Max	ns ns ns ns ns ns ns	
Write Command Setup Time	twcs	0	_	0	_	ns	10
Write Command Hold Time	twch	15	_	15	_	ns	
Write Command Pulse Width	twp	15	_	15	_	ns	
Write Command to RAS Lead Time	tRWL	20		20	_	ns	
Write Command to CAS Lead Time	tCWL	20	_	20		пѕ	
Data-in Setup Time	t _{DS}	0	_	0	_	ns	11
Data-in Hold Time	tDH	15	_	15	_	ns	11



Read-Modify-Write Cycle

Parameter	Symbol		HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Note
		Min	Max	Min	Max]	
Read-Modify-Write Cycle Time	t _{RWC}	185	_	220	_	ns	
RAS to WE Delay Time	tRWD	105	_	125	_	ns	10
CAS to WE Delay Time	tCWD	55	_	65	_	ns	10
Column Address to WE Delay Time	tAWD	70	_	80	-	ns	10, 13
OE Hold Time from WE	tOEH	15		15		ns	

Refresh Cycle

Parameter					HM511665-10 HM511665L-10		Note
		Min	Max	Min	Max		
CAS Setup Time (CAS Before RAS Refresh Cycle)	t _{CSR}	10	_	10	_	ns	
CAS Hold Time (CAS Before RAS Refresh Cycle)	t _{CHR}	10	_	10	_	ns	
RAS Precharge to CAS Hold Time	tRPC	10	_	10	_	ns	
CAS Precharge Time in Normal Mode	t _{CPN}	10		10	_	ns	

Fast Page Mode Cycle

Parameter	Symbol	HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Unit	Note
		Min	Max	Min	Max	1	
Fast Page Mode Cycle Time	t _{PC}	55	_	65	_	ns	
Fast Page Mode CAS Precharge Time	t _{CP}	10	_	10	_	ns	
Fast Page Mode RAS Pulse Width	tRASC	80	100000	100	100000	ns	12
Access Time from CAS Precharge	t _{ACP}	_	50	_	60	ns	3, 13
RAS Hold Time from CAS Precharge	†RHCP	45	_	55	-	ns	
Fast Page Mode Read-Modify- Write Cycle CAS Precharge to WE Delay Time	t _{CPW}	70	_	80	_	ns	
Fast Page Mode Read-Modify- Write Cycle Time	t _{PCM}	100	_	110	_	ns	

Counter Test Cycle

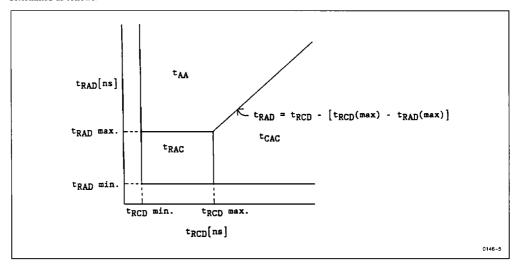
Parameter	Symbol	HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Unit	Note
		Min	Max	Min	Max		
CAS Precharge Time in Counter Test Cycle	t _{CPT}	40	_	40	_	пѕ	

Write Per Bit Cycle 16, 17

Parameter	Symbol	HM511665-8 HM511665L-8		HM511665-10 HM511665L-10		Unit	Note
		Min	Max	Min	Max		
Write per Bit Setup Time	twBS	0	_	0	_	ns	
Write per Bit Hold Time	twBH	10		10	_	ns	
Write per Bit Selection Setup Time	t _{WDS}	0		0		ns	
Write per Bit Selection Hold Time	twDH	10	_	10	_	ns	



- Notes: 1. AC measurements assume $t_T = 5$ ns.
 - Assumes that t_{RCD} ≤ t_{RCD} (max) and t_{RAD} ≤ t_{RAD} (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 - 3. Measured with a load circuit equivalent to 1 TTL load and 50 pF.
 - 4. Assumes that $t_{RCD} \ge t_{RCD}$ (max) and $(t_{RCD} t_{RAD}) \ge [t_{RCD}$ (max) t_{RAD} (max)].
 - 5. Assumes that $t_{RAD} \ge t_{RAD}$ (max) and $(t_{RCD} t_{RAD}) \le [t_{RCD} (max) t_{RAD} (max)]$. t_{RAC} , t_{CAC} , and t_{AA} are determined as follows:

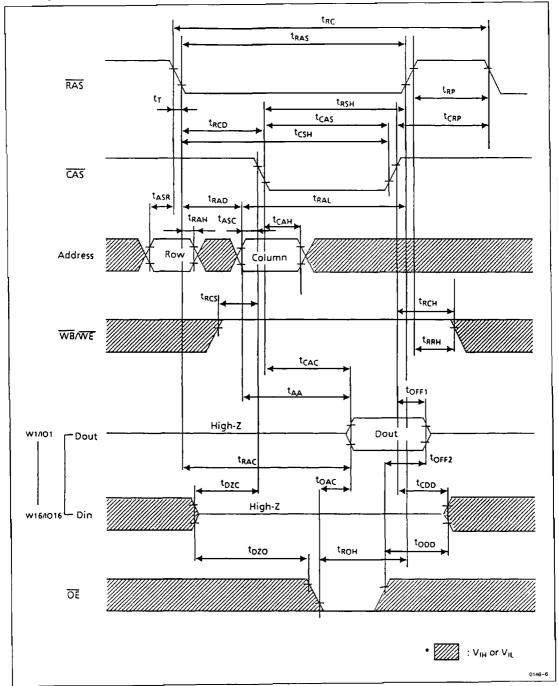


- 6. tOFF (max) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
- 7. VIH (min) and VIL (max) are reference levels for measuring timing of input signals. Also, transition times are measured between VIH and VIL.
- 8. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only, if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- 9. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only, if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
- 10. twcs, tRWD, tcWD and tAWD are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if twcs ≥ twcs (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if t_{RWD} ≥ t_{RWD} (min), t_{CWD} ≥ t_{CWD} (min), t_{AWD} ≥ t_{AWD} (min) and t_{CPW} ≥ t_{CPW} (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 11. These parameters are referenced to CAS leading edge in an early write cycle and to WE leading edge in a delayed write or a read-modify-write cycle.
- 12. t_{RASC} defines RAS pulse width in fast page mode cycles.
- 13. Access time is determined by the longer of tAA or tCAC or tACP.
- 14. An initial pause of 100 µs is required after power up followed by a minimum of eight initialization cycles (RAS only refresh cycle or CAS before RAS refresh cycle). If the internal refresh counter is used, a minimum of eight CAS before RAS refresh
- 15. In delayed write or read-modify-write cycles, OE must disable output buffer prior to applying data to the device.
- 16. When using the write-per-bit capability, WB/WE must be low as RAS falls.
- 17. The data bits to which the write operation is applied can be specified by keeping Wi/IOi high with setup and hold time referenced to the RAS negative transition.

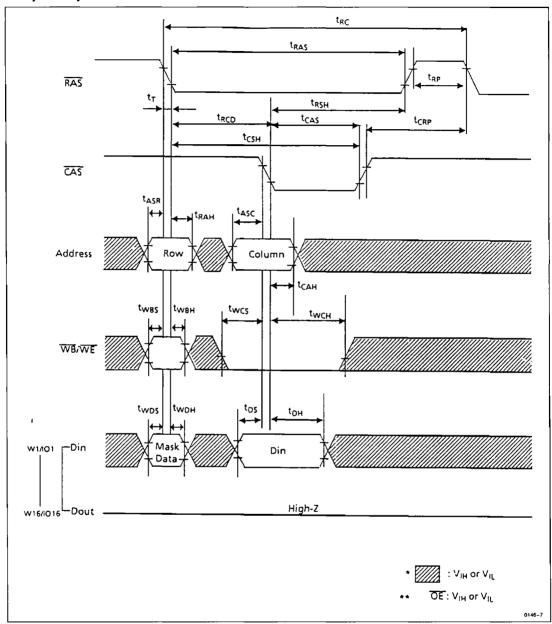


■ TIMING WAVEFORMS

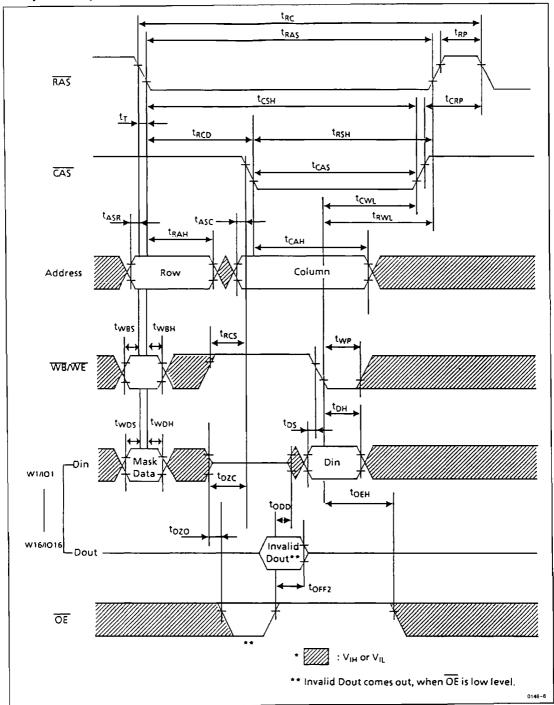
• Read Cycle



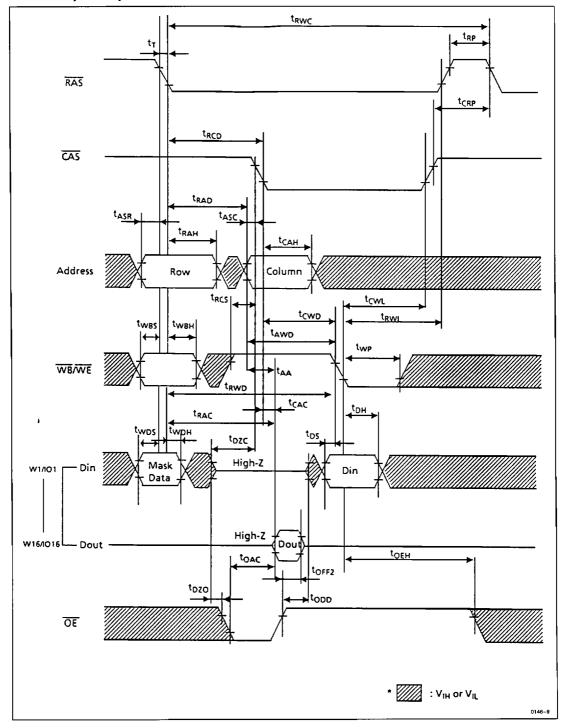
• Early Write Cycle



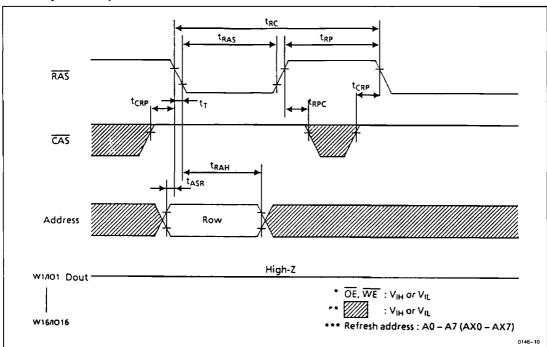
• Delayed Write Cycle



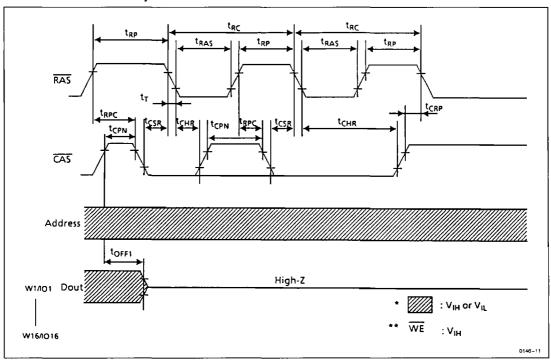
• Read-Modify-Write Cycle



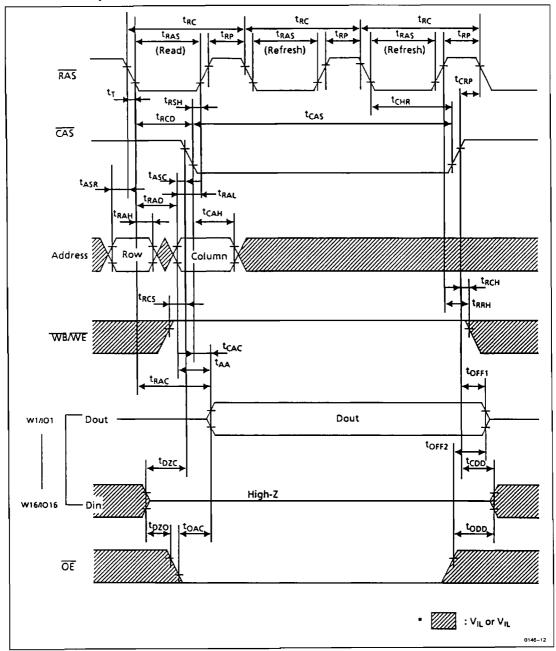
• RAS Only Refresh Cycle



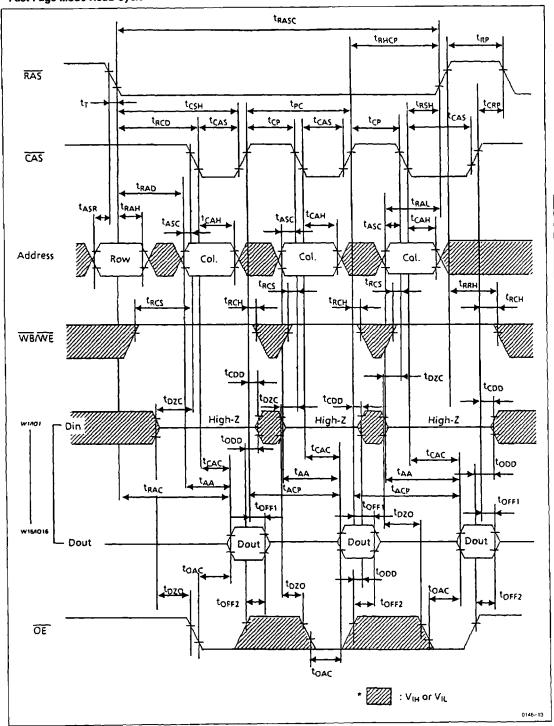
• CAS Before RAS Refresh Cycle



• Hidden Refresh Cycle

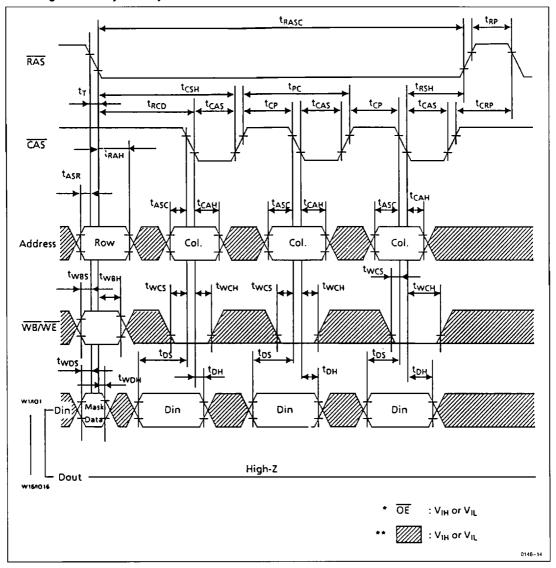


• Fast Page Mode Read Cycle

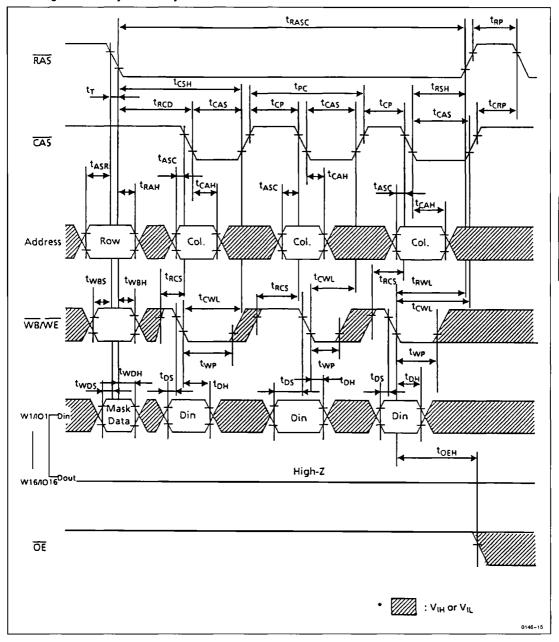


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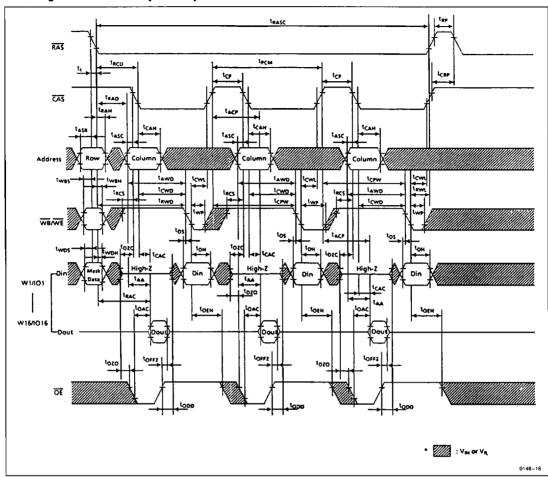
• Fast Page Mode Early Write Cycle



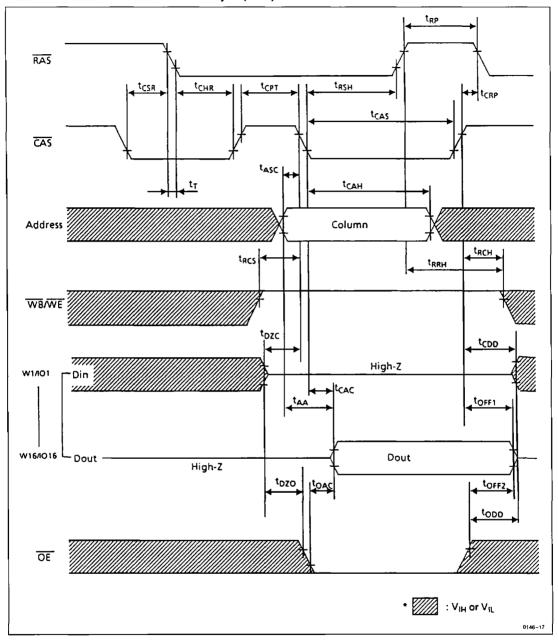
• Fast Page Mode Delayed Write Cycle



• Fast Page Mode Read-Modify-Write Cycle



• CAS Before RAS Refresh Counter Check Cycle (Read)



• CAS Before RAS Refresh Counter Check Cycle (Write)

